TOSHIBA Bipolar Linear Integrated Circuit Silicon Monolithic

TA6039FN

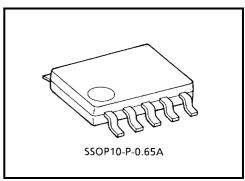
Shock Sensor IC

TA6039FN detects an existence of external shock through the shock sensor and output.

Compared with TA6009FN, S/N ratio is improved by 8dB. It is suitable for applications which require low-noise operation.

Features

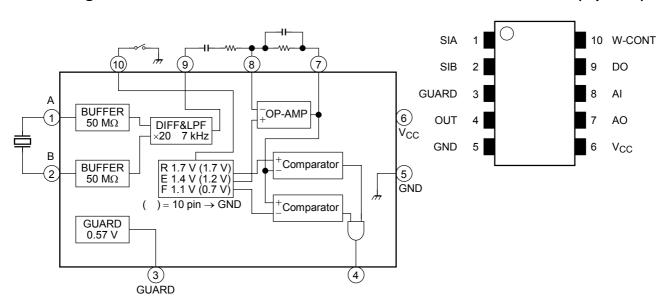
- TA6039FN operates from 2.7 to 5.5 V DC single power supply voltage.
- Signal from the shock sensor is amplified according to setting gain, and is detected through the internal window comparator.
- TA6039FN incorporates 1-ch shock detecting circuitry.
- Input terminal of sensor signal is designed high impedance. Differential input impedance = $100 \text{ M}\Omega$ (typ.)
- LPF (low pass filter) circuitry is incorporated. Cut-off frequency of LPF = 7 kHz
- Sensitivity of shock detection can be adjusted by external devices.
- Small package SSOP10-P-0.65A (0.65 mm pitch)



Weight: 0.04 g (typ.)

Block Diagram

Pin Connection (top view)



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Pin Function

Pin No.	Pin Name	Function
1	SIA	Connection terminal of shock sensor
2	SIB	Connection terminal of shock sensor
3	GUARD	Input (1, 2 pin) GUARD terminal
4	OUT	Output terminal (output = "L" when shock is detected.)
5	GND	Ground terminal
6	V _{CC}	Power supply voltage
7	AO	Op-Amp output terminal
8	Al	Op-Amp input terminal
9	DO	Differential-Amp output terminal
10	W-CONT	Window-comparator trip voltage selection terminal.

Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Power supply voltage	V _{CC}	7	V
Power dissipation	P_{D}	300	mW
Storage temperature	T _{stg}	-55 to 150	°C

Recommend Operating Condition

Characteristics	Symbol	Rating	Unit
Power supply voltage	V _{CC}	2.7 to 5.5	V
Operating temperature	T _{opr}	-25 to 85	°C

Note: The IC may be destroyed due to short circuit between adjacent pins, incorrect orientation of device's mounting, connecting positive and negative power supply pins wrong way round, air contamination fault, or fault by improper grounding.

Electrical Characteristics (unless otherwise specified, $V_{CC} = 3.3 \text{ V}$, $Ta = 25^{\circ}\text{C}$)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Supply voltage	V _{CC}	_		2.7	3.3	5.5	V
Supply surrent	Icc	(1)	$V_{CC} = 3.3 \text{ V}$		1.8	2.6	mA
Supply current			V _{CC} = 5.0 V		1.8	2.7	

(GUARD)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Output voltage	VoGur	(2)		0.52	0.57	0.62	V

(DIFF-AMP)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Input impedance (Note 1)	Zin	_		30	100		ΜΩ
Gain	GvBuf	(3)		25.6	26.0	26.4	dB
Output DC voltage	VoBuf	(4)	Connect C = 100 pF between 1 pin, 2 pin and 3 pin	0.7	1	1.3	٧
Low pass filter cut-off frequency	fc	(5)	Frequency at -3dB point	5	7	10	kHz
Output source current	IB _{so}	(6)	Voh = V _{CC} – 1 V	350	800		μА
Output sink current	IB _{si}	(7)	Vol = 0.3 V	75	130		μΑ

(OP-AMP)

Characteristics		Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Cut-off frequency	(Note 1)	fT	_		1.5	2		MHz
Openloop gain	(Note 1)	Gvo	_		80	90		dB
Input voltage 1		Vin1	(8)	10 pin → OPEN (Note 2) 1.33	1.4	1.47	V
Input voltage 2		Vin2	(9)	10 pin → GND (Note 2	1.14	1.2	1.26	V
Input current		lin	(10)			25	50	nA
Offset voltage	(Note 1)	Voff	_		-5	0	5	mV
Output source current		IA _{so}	(11)	Voh = V _{CC} – 1 V	300	800		μА
Output sink current		IA _{si}	(12)	Vol = 0.3 V	130	200		μА

(Window-Comparator)

Characteristics		Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Trip voltage 1	(Note 1)	Vtrp1	_	10 pin → OPEN (Note	2) Vin1 ±0.285	Vin1 ±0.3	Vin1 ±0.315	٧
Trip voltage 2	(Note 2)	Vtrp2	_	10 pin → GND (Note	2) Vin2 ±0.475	Vin2 ±0.5	Vin2 ±0.525	٧
Output source current		IW _{so}	(13)	$Voh = V_{CC} - 0.5 V$	30	50		μА
Output sink current		IW _{si}	(14)	Vol = 0.3 V	300	800		μΑ

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Note 1: Marked parameters are reference data.

Note 2: 10 pin must be non-connected otherwise connected to GND.

Application Note

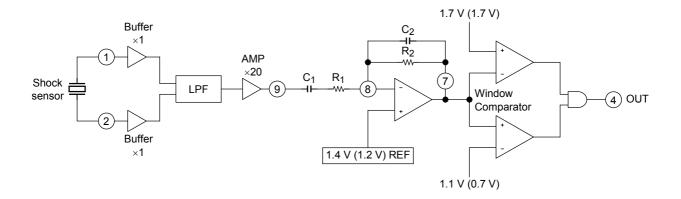


Figure 1 The Composition of G-Force Sense Amplifier

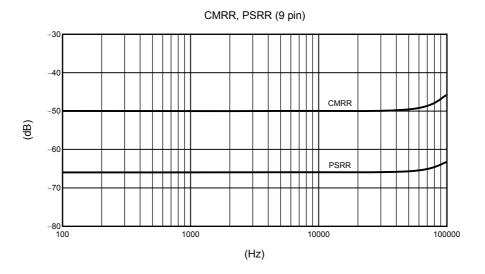
Figure 1 shows the configuration of G-Force sensor amplifier. The shock sensor is connected between the pins 1 and 2. External registor R₁ and R₂ are used to adjust the sensitivity.

When G-force Sensor (sensor sensibility = s (mV/G)) is used to detect external shock of g (G), the external parts are determined as following.

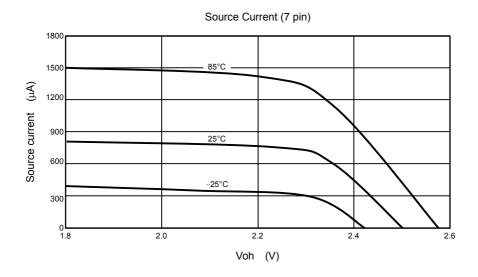
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(gain setting) * 10 PIN \rightarrow GND 500/(s \times g) = G1 G1/20 = G (OP-AMP) (HPF setting) fc = 1/(2 \pi \times R_1 \times C_1) (LPF setting) fc = 1/(2 \pi \times R_2 \times C_2)
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Reference Data

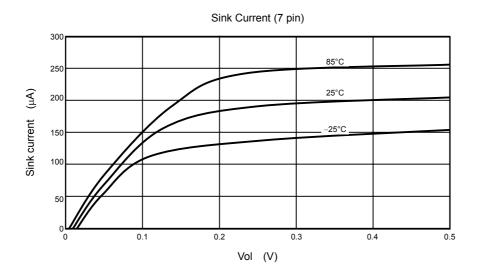
(1) 9 pin (DIFF-AMP output) CMRR, PSRR



(2) 7 pin (OP-AMP output) source current

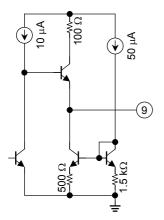


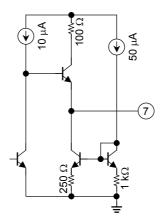
(3) 7 pin (OP-AMP output) sink current

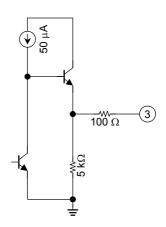


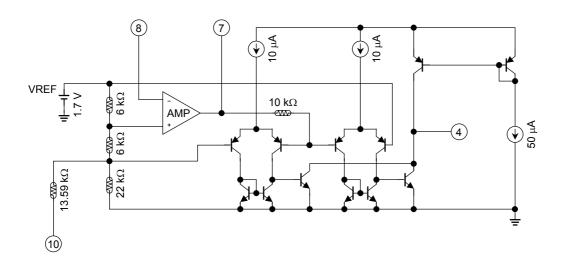
TA6039FN

Equivalent Circuit







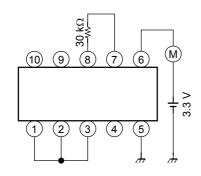


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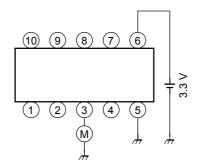
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Test Circuit

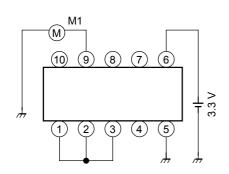
(1) Supply current ICC



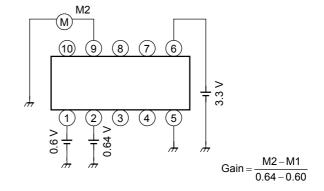
(2) GUARD Pin Output voltage **VoGur**



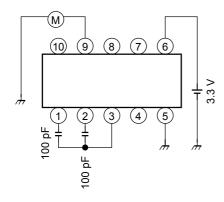
(3) DIFF-AMP Gain **GvBuf** Step 1



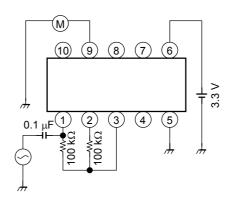
Step 2



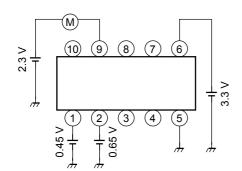
(4) DIFF-AMP Output DC voltage **VoBuf**



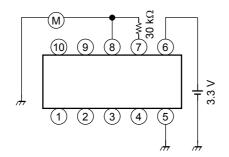
(5) DIFF-AMP Low cut-off frequency **fc**



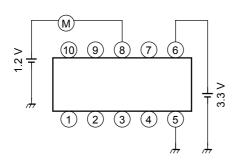
(6) DIFF-AMP
Output source current **IBso**



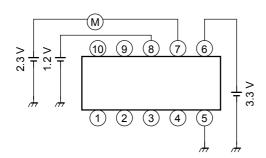
(8) OP-AMP Input voltage 1 **Vin1**



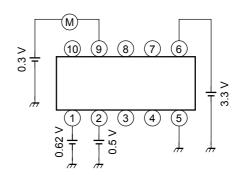
(10) OP-AMP Input current **I**in



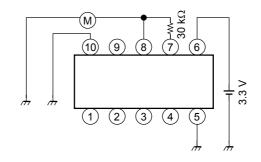
(11) OP-AMP Output source current **IAso**



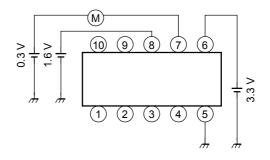
(7) DIFF-AMP Output sink current **IBsi**



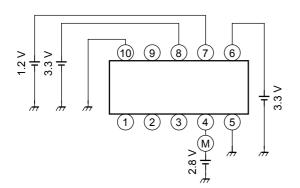
(9) OP-AMP Input voltage 2 **Vin2**



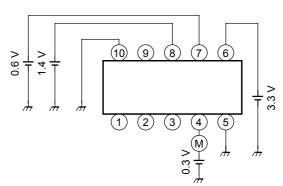
(12) OP-AMP Output sink current **IAsi**



(13) Window comparator Output source current **IWso**

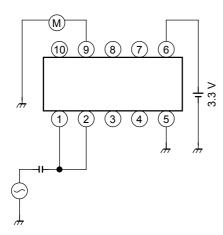


(14) Window comparator Output sink current **IWsi**

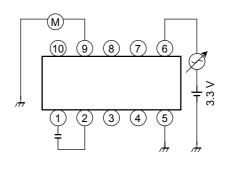


Test Circuit (for reference)

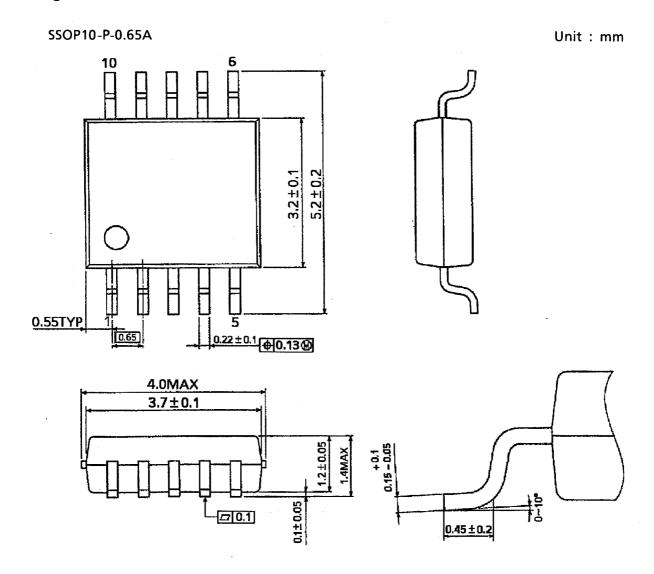
(a) DIFF-AMP **CMRR**



(b) DIFF-AMP **PSRR**



Package Dimensions



Weight: 0.04 g (typ.)

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